



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
-----------------	-------------	----------------------	---------------------	------------------

10/586,598

07/20/2006

Tadashi Maeda

2006_1151A

1659

513 7590 07/15/2011
WENDEROTH, LIND & PONACK, L.L.P.
1030 15th Street, N.W.,
Suite 400 East
Washington, DC 20005-1503

EXAMINER

MEHTA, MEGHA S

ART UNIT

PAPER NUMBER

1783

NOTIFICATION DATE

DELIVERY MODE

07/15/2011

ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

ddalecki@wenderoth.com
coa@wenderoth.com

Art Unit: 1783

Request for Reconsideration

1. The request for reconsideration has been considered but does NOT place the application in condition for allowance because:

2. Applicant argues that the Examiner is inconsistent in referring to the modification of Mei in view of Kang. However, as stated in the remarks, the Examiner never suggested a modification of Mei's solder ***composition***, only the ***shape*** of the metal powders. This is not inconsistent with either statement: the composition has not been modified, but the flake-shaped powders have been included in the combination.

3. Applicant next argues that Mei's solder composition does not meet the limitations of the claim because after melting, there are no particles left in the solder. However, this is incorrect because the solder must re-solidify. It does not stay in a liquid state forever. The solder is melted and then cooled to become solid again after the reflow process. Therefore, in the resolidification process, the metal particles nucleate and grow until all of the solder has been solidified. Therefore, after the solidification process, the particles in the solder have returned. Furthermore, please note that the claim as written does not require the scales to be in the solder composition after the reflow process, only before.

4. For these reasons, all previous rejections, including the double patenting, have been maintained.

/Megha Mehta/
Examiner, Art Unit 1783

/David R. Sample/
Supervisory Patent Examiner, Art Unit 1783